

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hsi-Yu Kuo</td> <td>04/27/2012</td> </tr> <tr> <td>Chi-Kuang Chen</td> <td>04/27/2012</td> </tr> </tbody> </table>		Name	Execution Date	Hsi-Yu Kuo	04/27/2012	Chi-Kuang Chen	04/27/2012				
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<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Company, Ltd.</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Road 6</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Company, Ltd.	Street Address:	No. 8, Li-Hsin Road 6	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77
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PROPERTY NUMBERS Total: 1											
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CORRESPONDENCE DATA											
<p>Fax Number: (214)200-0853 Phone: 214-651-5000 Email: ipdocketing@haynesboone.com <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: HAYNES AND BOONE, LLP Address Line 1: 2323 Victory Avenue Address Line 2: Suite 700 Address Line 4: Dallas, TEXAS 75219</p>											
ATTORNEY DOCKET NUMBER:	24061.2157										
NAME OF SUBMITTER:	Eric Q. Li										
Total Attachments: 2 source=2157_Assignment#page1.tif source=2157_Assignment#page2.tif											

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|----------------|----|---|
| (1) | Hsi-Yu Kuo | of | 3F-3, No. 38, Lane 579, Sec. 1, Guangfu Road, East District
Hsinchu City 300, Taiwan, R.O.C. |
| (2) | Chi-Kuang Chen | of | 14F, No. 1, Lane 32, Zhangxin Street, Wenshan District
Taipei City 116, Taiwan, R.O.C. |

have invented certain improvements in

AN IMPROVED AND TUNABLE ESD PROTECTION DEVICE

for which we have filed an application for Letters Patent of the United States of America on
May 11, 2012, as U.S. Serial No. 13/469,923; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

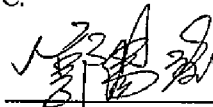
AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Hsi-Yu Kuo

Residence Address: 3F-3, No. 38, Lane 579, Sec. 1, Guangfu Road, East District
Hsinchu City 300, Taiwan, R.O.C.

Dated: ✓

Apr. 27, 2012

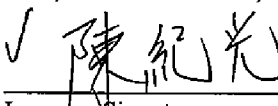
✓  Hsi-Yu Kuo
Inventor Signature

Inventor Name: Chi-Kuang Chen

Residence Address: 14F, No. 1, Lane 32, Zhangxin Street, Wenshan District,
Hsin-Chu, Taiwan, R.O.C.

Dated: ✓

Apr. 27, 2012

✓  Chi-Kuang Chen
Inventor Signature